

# PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
<b>CONVEYING PARTY DATA</b>													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Kang Chen</td> <td>09/20/2010</td> </tr> <tr> <td>Xusheng Bao</td> <td>09/20/2010</td> </tr> <tr> <td>Rui Huang</td> <td>09/20/2010</td> </tr> <tr> <td>Yung Kuan Hsiao</td> <td>09/20/2010</td> </tr> <tr> <td>Hin Hwa Goh</td> <td>09/20/2010</td> </tr> </tbody> </table>		Name	Execution Date	Kang Chen	09/20/2010	Xusheng Bao	09/20/2010	Rui Huang	09/20/2010	Yung Kuan Hsiao	09/20/2010	Hin Hwa Goh	09/20/2010
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<b>CORRESPONDENCE DATA</b>													
<p>Fax Number: (408)738-0881  <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 408-738-0592        Email: <a href="mailto:efiling@ishimarulaw.com">efiling@ishimarulaw.com</a>        Correspondent Name: LAW OFFICES OF MIKIO ISHIMARU        Address Line 1: 333 W. EL CAMINO REAL        Address Line 2: SUITE 330        Address Line 4: SUNNYVALE, CALIFORNIA 94087</p>													
ATTORNEY DOCKET NUMBER:	27-733												

CH \$40.00 12887681

**501306990**

**PATENT  
 REEL: 025070 FRAME: 0987**

NAME OF SUBMITTER:

Mikio Ishimaru

Total Attachments: 3

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## ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

### **INTEGRATED CIRCUIT PACKAGING SYSTEM WITH ACTIVE SURFACE HEAT REMOVAL AND METHOD OF MANUFACTURE THEREOF**

for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, STATS ChipPAC Ltd., a Corporation of the Republic of Singapore, having a place of business at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, Republic of Singapore (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;



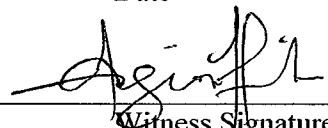
NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee(s), the receipt of which is hereby acknowledged by said Assignor(s):

1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee(s), the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee(s) where said Assignee(s) may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee(s).
3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee(s), its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.
4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.




5. Said Assignor(s) hereby authorizes and requests the attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

Serial Number: 12/887,681 Filing Date: September 22, 2010



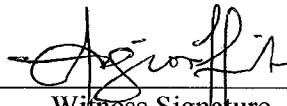
IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

<u></u>	<u>20-Sep-2010</u>
Kang Chen	Date
<u></u>	<u></u>
Witness Signature	Witness Signature
<u>LIM LEE SUN</u>	<u>DIOSCORO MERILLO</u>
Print Witness Name	Print Witness Name
<u>20-Sep-2010</u>	<u>20 SEPT. 2010</u>
Date	Date

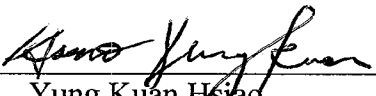


IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

<u></u>	<u>20 Sept 2010</u>
Xusheng Bao	Date
<u></u>	<u></u>
Witness Signature	Witness Signature
<u>LIM LEE SUN</u>	<u>DIOSCORO MERILLO</u>
Print Witness Name	Print Witness Name
<u>20-Sep-2010</u>	<u>20 SEPT. 2010</u>
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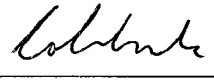


IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

 _____ Rui Huang	<u>20 - Sep - 2010</u> _____ Date
 _____ Witness Signature	 _____ Witness Signature
<u>LIM LEE SUN</u> _____ Print Witness Name	<u>DIOSCORO MERILO</u> _____ Print Witness Name
<u>20-Sep-2010</u> _____ Date	<u>20 SEPT. 2010</u> _____ Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

 _____ Yung Kuan Hsiao	<u>20-Sep-2010</u> _____ Date
 _____ Witness Signature	 _____ Witness Signature
<u>LIM LEE SUN</u> _____ Print Witness Name	<u>DIOSCORO MERILO</u> _____ Print Witness Name
<u>20-Sep-2010</u> _____ Date	<u>20 SEPT. 2010</u> _____ Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

 _____ Hin Hwa Goh	<u>20 Sept 2010</u> _____ Date
 _____ Witness Signature	 _____ Witness Signature
<u>LIM LEE SUN</u> _____ Print Witness Name	<u>DIOSCORO MERILO</u> _____ Print Witness Name
<u>20-Sep-2010</u> _____ Date	<u>20 SEPT. 2010</u> _____ Date